
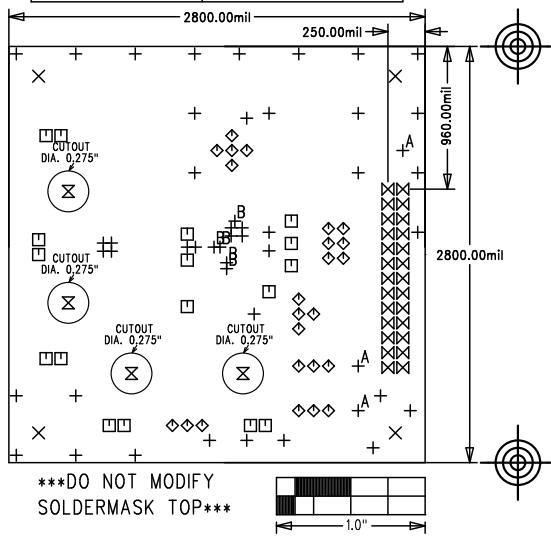
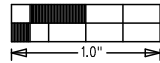


MAX98357 WLP EVKIT - DEVELOPMENT BOARD	
P/N: EPCB98357DEVWLP	REV A
 maxim integrated™	
LAYER	DRILL & MECHANICALS
DATE:	ALL UNITS ARE IN 0.001"



***DO NOT MODIFY
SOLDERMASK TOP***



SIZE	QTY	SYM	PLATED	TOL
25	41	+	YES	+/-3
125	4	X	YES	+/-3
40	17	□	YES	+/-3
37	24	◇	YES	+/-3
275	4	⊗	YES	+/-3
43.31	26	⊗	YES	+/-3
67	3	+ ^A	YES	+/-3
15	5	+ ^B	YES	+/-3

NOTES: UNLESS OTHERWISE SPECIFIED

- FABRICATE USING PROVIDED GERBER FILES PER LATEST REVISION OF IPC-A-600 UNLESS OTHERWISE NOTED.
- MATERIAL: RoHS COMPLIANT FR-408 OR SIMILAR LAMINATE MATERIAL WITH $T_g \geq 170$ AND COMPATIBLE WITH LEAD-FREE SOLDERING PROCESS.
- BOARD DIMENSIONS: 2.80"X2.80" +/- 0.010".
BOARD THICKNESS: 0.062"
- LAYERS: 4. SEE LAYER STACKUP CHART.
- MINIMUM TRACE/SPACING: 2.5MILS/3MILS.
- COPPER CLAD FINISH: 1oz ON ALL LAYERS.
- SURFACE MOUNT PADS: 62.
- SOLDERMASK: GREEN, TAIYO PSR-4000.
SOLDERMASK APERTURE TOLERANCE: +/-0.0005".
- LEGENDS: WHITE, SINGLE-SIDED, NON-CONDUCTIVE EPOXY INK OR EQUIVALENT.
CLIPPED ALL LEGENDS FROM EXPOSED METAL.
- PLATING: MUST BE LEAD FREE AND RoHS COMPLIANT.
- FINISH: 3-8u" IMMERSION Au OVER 100u" Ni.
- VENDOR LOGO & DATE CODE REQUIRED IN INK ON BOTTOM SIDE ONLY. DATE CODE FORMAT MUST BE YYWW ONLY.
- THRU HOLES: 0.001" MIN.
- TOLERANCES:
PLATED-THRU HOLES: +/-0.003"
PATTERN-TO-PATTERN: +/-0.005"
LEGEND TO LEGEND: +/-0.007"

LAYER 1 TOP	1.4MIL
/PRE-PREG AS NEEDED $E_r=3.8$	
LAYER 2 GND	1.4MIL
CORE AS NEEDED $E_r=3.8$	
LAYER 3 PWR/GND	1.4MIL
/PRE-PREG AS NEEDED $E_r=3.8$	
LAYER 4 BOTTOM	1.4MIL

ALL DIMENSION IN MIL (0.001 INCH) UNLESS OTHERWISE SPECIFIED.